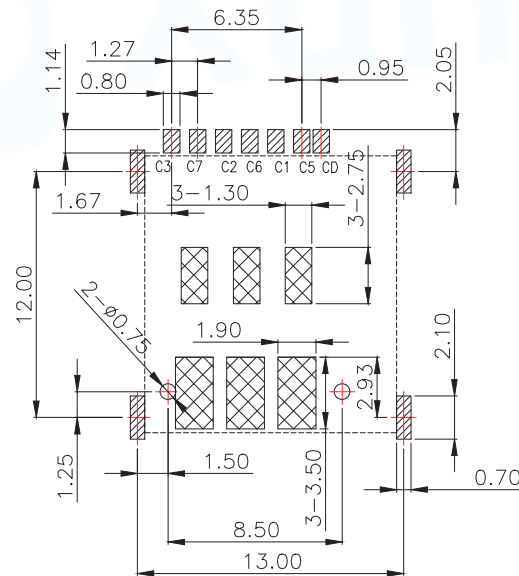
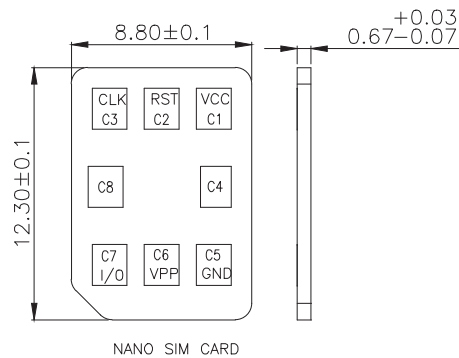
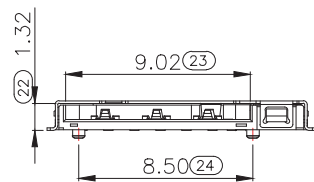
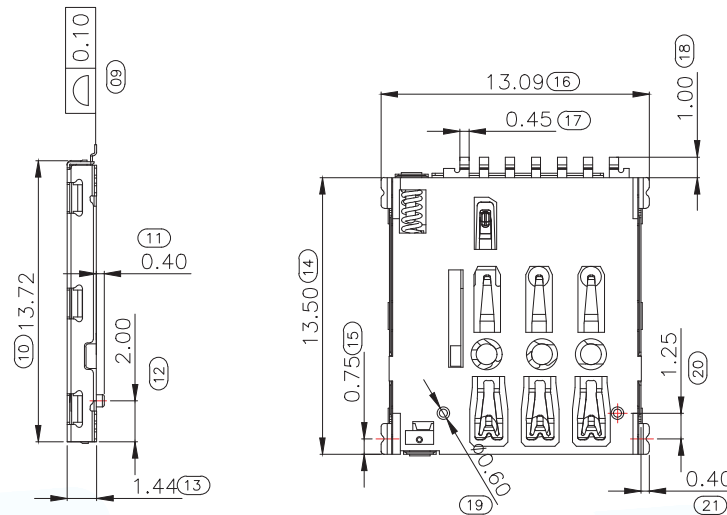
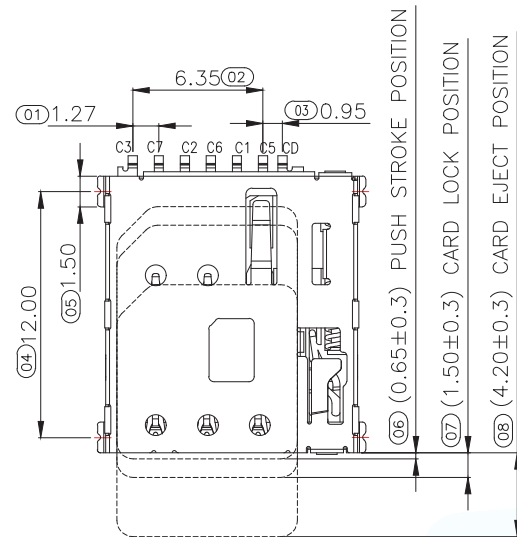


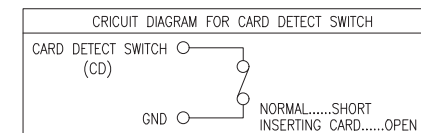


RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ± 0.05

▨ PAD
▨ KEEP OUT AREA

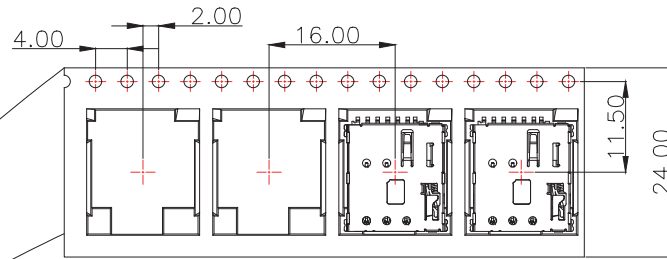
- NOTES:
- 1) MATERIAL:
HOUSING: HI-TEMP. PLASIC UL 94V-0
CONTACT: COPPER ALLOY
SHELL: STAINLESS STEEL
 - 2). PLATING :
TERMINAL:
CONTACT AREA: Au GOLD FLASH.
SOLDER AREA: AU GOLD FLASH.
UNDER PLATE: NICKEL.
SHELL: NICKEL PLATED OVER ALL.
SOLDER AREA: GOLD FLASH.
 3. SPECIALITY:
3.1 Rated current: 1.0A
3.2 Rated voltage: 30V
3.3 Contact Resistance: 50mΩ MAX
3.4 Insulation Resistance: 1000MΩ MIN 500V DC
3.5 Dielectric withstanding voltage: 500V AC.
3.6 Solder ability: 260±0/-5℃, 30±10s.
3.7 Durability: 5000 Cycles Min.
3.8 Operating condition: Temperature -40℃~+85℃;
Humidity 80% R.H MAX

SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



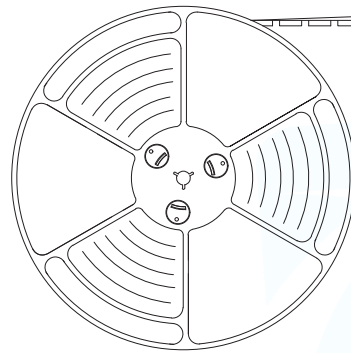
MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES		TITLE: NANO SIM CARD 1.37H PUSH PUSH 有柱	
DECIMALS:		PAR	SWN-303S-ACP7
ANGLES:		DWN	
X.: ±0.35		CHKD	
.X.: ±0.15		APVD	
.XX.: ±0.10		SCALE: 1:1	UNIT: MM
CUSTOMER COPY		SIZE: A4	SHEET: 1F1
			REV: A

客户拉出方向



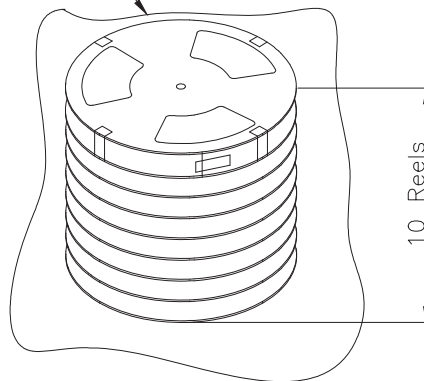
客户拉出方向

自粘上贴



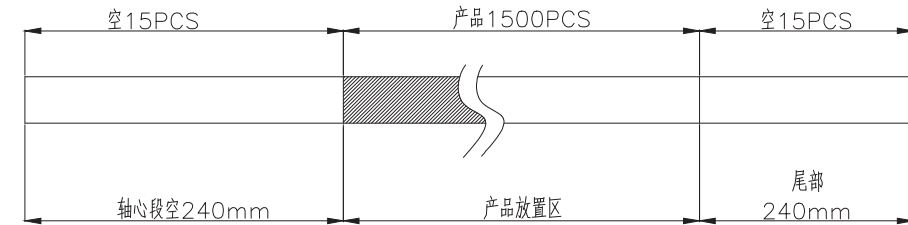
PE袋

纸箱底部和顶部各垫一块珍珠棉



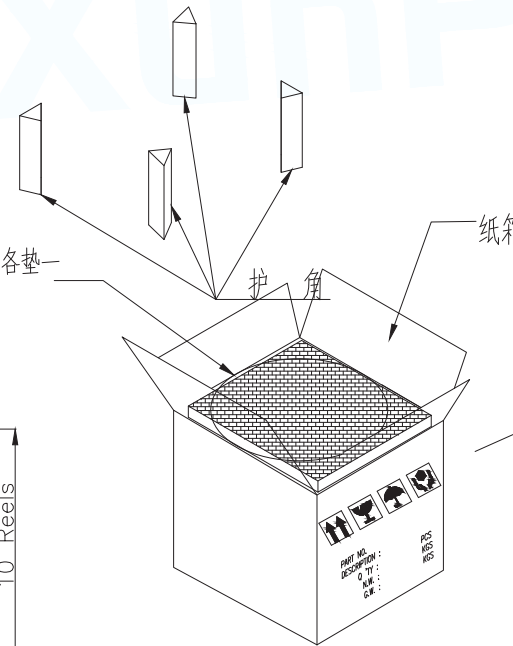
NOTES

- 1.每卷包装数量:1500PCS/每卷
- 2.卷带包装方式:

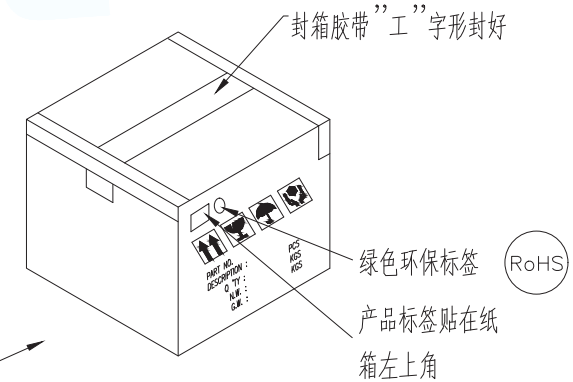


- 3.每箱包装数量:15000PCS/箱

- 4.纸箱350mm*350mm*340mm(内部尺寸),材质K=K



将10卷产品放入箱内



MANUFACTURE DWG		 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES		TITLE:NANO SIM CARD 1.37H PUSH PUSH 有柱 包装图	
DECIMALS:		PAR	
X.:±0.35		SMN-303S-ACP7	
.X.:±0.15		DWN	
.XX:±0.10		CHKD	
ANGLES:		APVD	
X":±2°		SCALE 1:1	
.X":±1°		UNIT:MM	
.XX":±0.5°		SIZE:A4	
CUSTOMER COPY		SHEET:2F2	
		REV:A	